SCES108G-JULY 1997-REVISED NOVEMBER 2004

FEATURES

- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 2.8 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

D, DGV, NS, OR PW PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This quadruple 2-input positive-OR gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVC32 performs the Boolean function $Y = \overline{A \cdot B}$ or Y = A + B in positive logic.

ORDERING INFORMATION

T _A	PAC	CKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
4000 11 0500	Tube		SN74ALVC32D	ALVC32	
	SOIC - D	Tape and reel	SN74ALVC32DR	ALVC32	
	SOP - NS	Tape and reel	SN74ALVC32NSR	ALVC32	
-40°C to 85°C	TSSOP - PW	Tube	SN74ALVC32PW	V/A22	
	1330P - PW	Tape and reel	SN74ALVC32PWR	VA32	
	TVSOP - DGV	Tape and reel	SN74ALVC32DGVR	VA32	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

	INP	UTS	OUTPUT
H	Α	В	Y
	Н	Х	Н
	X	Н	Н
	L	L	L

LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)



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SN74ALVC32 QUADRUPLE 2-INPUT POSITIVE-OR GATE





ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current		±50	mA	
	Continuous current through V _{CC} or GND		±100	mA	
		D package		86	
	Package thermal impedance ⁽⁴⁾	DGV package		127	°C/W
θ_{JA}		NS package		76	
		PW package		113	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT	
V_{CC}	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage	,	0	3.6	V	
Vo	Output voltage		0	V _{CC}	V	
		V _{CC} = 1.65 V		-4		
	High-level output current	V _{CC} = 2.3 V		-12		
I _{OH}		V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
	Low level output ourrent	V _{CC} = 2.3 V		12	A	
l _{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate			5	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ M	AX	UNIT
	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			
	I _{OH} = -4 mA	1.65 V	1.2			
	I _{OH} = -6 mA	2.3 V	2			
V _{OH}		2.3 V	1.7			V
	I _{OH} = -12 mA	2.7 V	2.2			
		3 V	2.4			
	I _{OH} = -24 mA	3 V	2			
	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	
	I _{OL} = 4 mA	1.65 V		0	45	
	I _{OL} = 6 mA	2.3 V			0.4	V
V _{OL}	12 m/	2.3 V			0.7	V
	I _{OL} = 12 mA	2.7 V			0.4	
	I _{OL} = 24 mA	3 V		0	.55	
I _I	$V_I = V_{CC}$ or GND	3.6 V			±5	μΑ
I _{cc}	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			10	μΑ
ΔI_{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		7	50	μΑ
C _i	V _I = V _{CC} or GND	3.3 V		4		pF

⁽¹⁾ All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0	2.5 V .2 V	V _{CC} =	2.7 V	V _{CC} = ± 0.3	3.3 V 3 V	UNIT
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Υ	1	4.7	1	3.1		2.9	1	2.8	ns

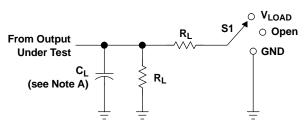
OPERATING CHARACTERISTICS

 $T_A = 25^{\circ}C$

	PARAMETER		AMETER TEST CONDITIONS		V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance per gate	$C_{L} = 0$,	f = 10 MHz	23	24	26	pF



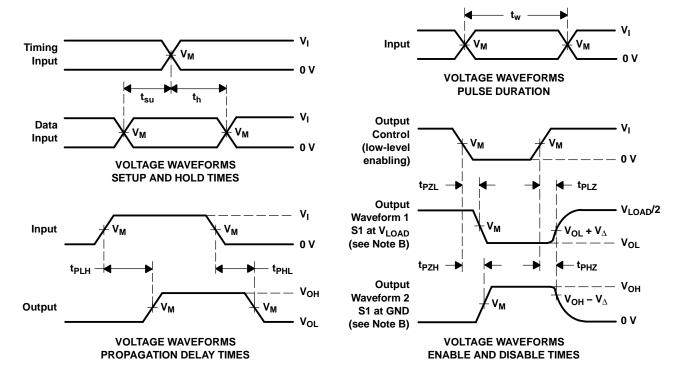
PARAMETER MEASUREMENT INFORMATION



TEST	S 1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

v	INPUT		V	V	CL	C	v
V _{CC}	VI	t _r /t _f	VΜ	V _M V _{LOAD}		R _L	$oldsymbol{V}_\Delta$
1.8 V ± 0.15 V	v _{cc}	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

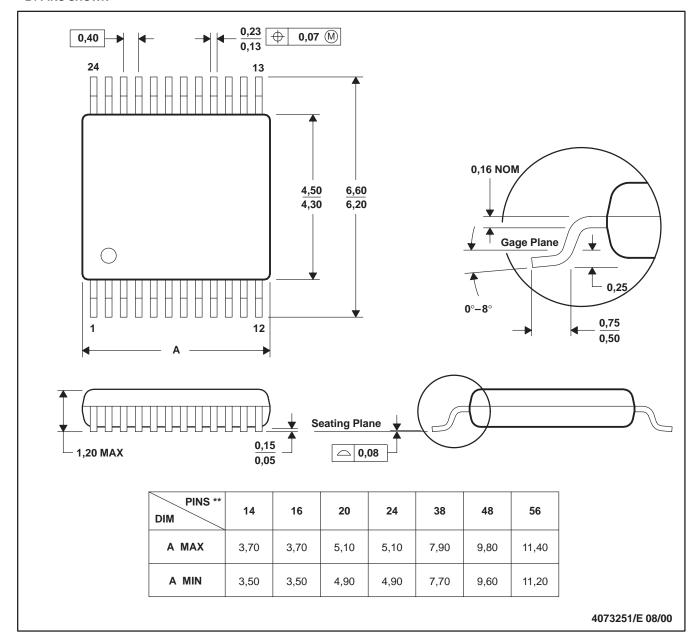
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \ \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



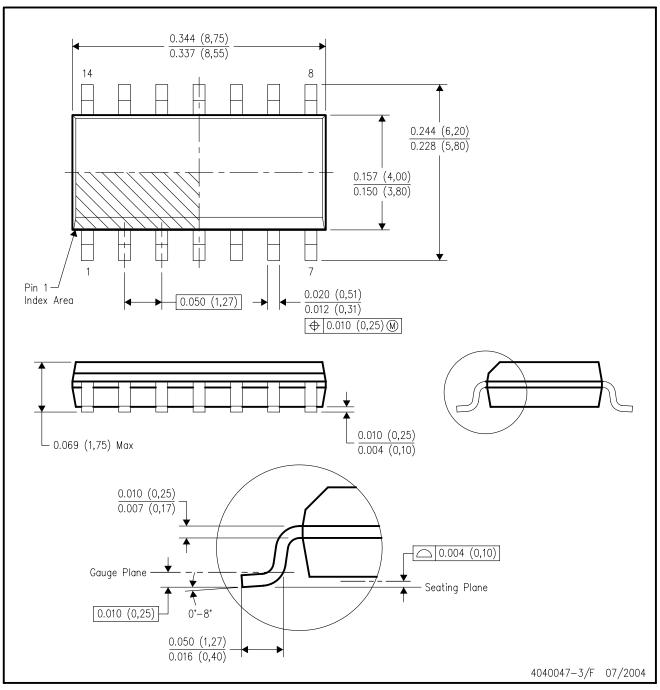
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.

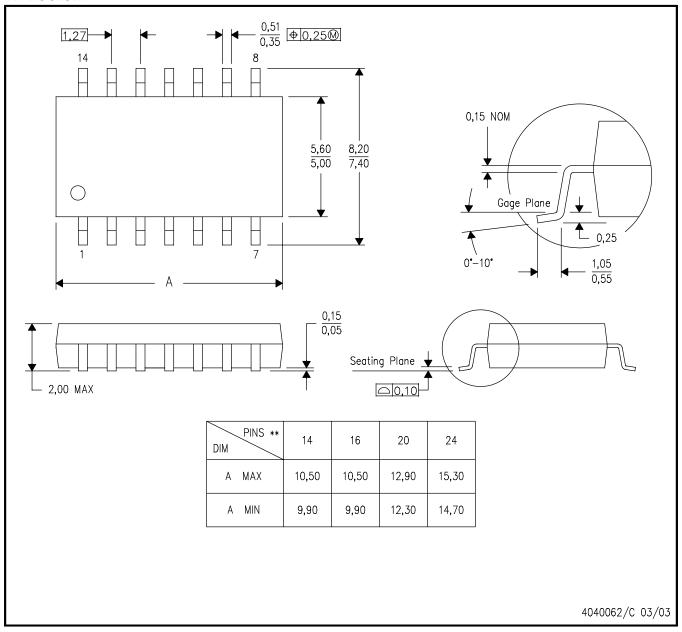


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

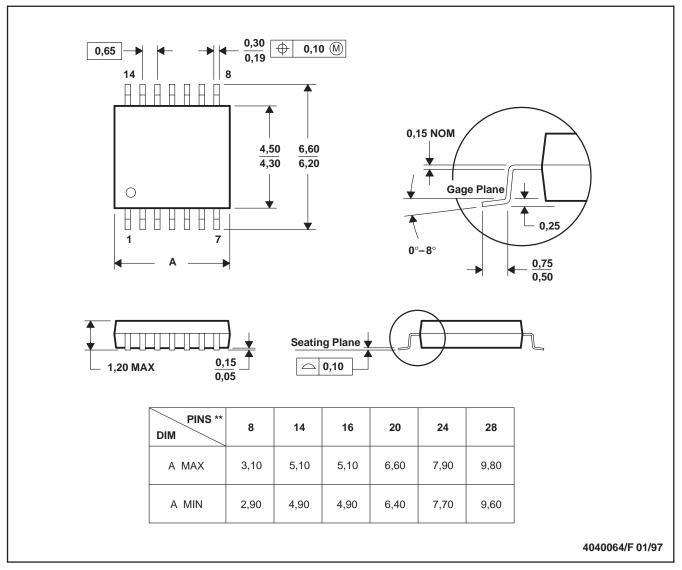
- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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